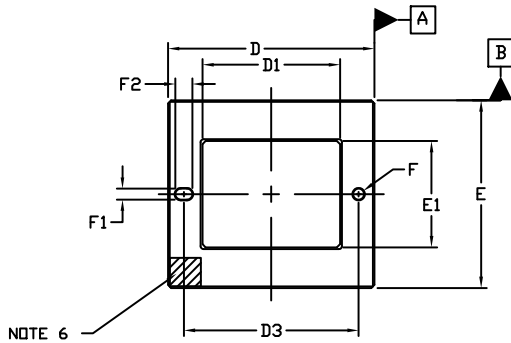


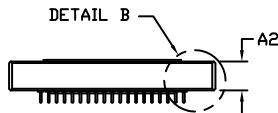


**CPGA143 33x30**  
**CASE 107FE**  
**ISSUE O**

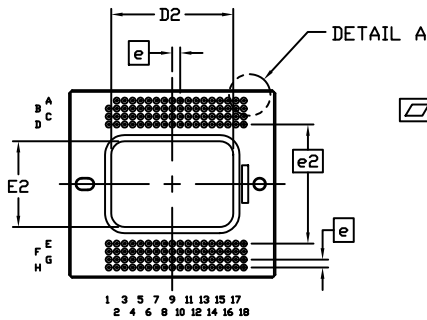
DATE 23 JUN 2016



TOP VIEW



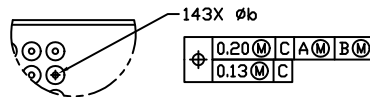
SIDE VIEW



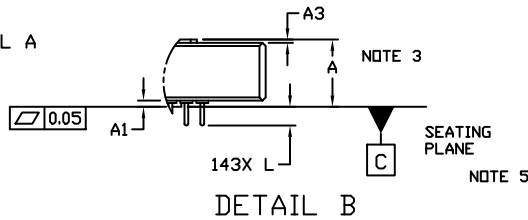
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. THE SEATING PLANE IS DEFINED BY THE OUTER HEATSINK SURFACE.
6. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.



DETAIL A



DETAIL B

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	6.38
A1	0.04	0.96
A2	4.15	5.07
A3	0.27	REF
b	0.17	0.43
D	32.97	33.33
D1	22.00	REF
D2	19.41	19.61
D3	27.66	28.22
E	29.87	30.13
E1	17.00	REF
E2	13.60	13.80
e	1.27	BSC
F	1.65	1.85
F1	1.65	1.85
F2	2.57	2.87
L	1.00	2.00

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DESCRIPTION:	CPGA143 33X30	PAGE 1 OF 2

